

## PCN – Process Change Notification

Change:	PA/SGP/SGGP/ILA/GLA/GGBLA Series Products
Date:	2016/09/08
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### Affected Products

Model#	Part Number	Changes
PA Series	-	Amend Package. (follow MSL III)
SGP Series		
SGGP Series		
ILA Series		
GLA Series		
GGBLA Series		

### Type of Change

- Hardware Modification  
 Production Process Advance  
 Others –Amend Package

### Description of Change

- Amend Package (follow MSL III), in order to keep Taoglas SMT series products have good storage conditions before it using. The package need to be put desiccant and humidity indicator card into the vacuum bag. And, we will mark the package standard follow the MSL III level labels on the packaging carton.

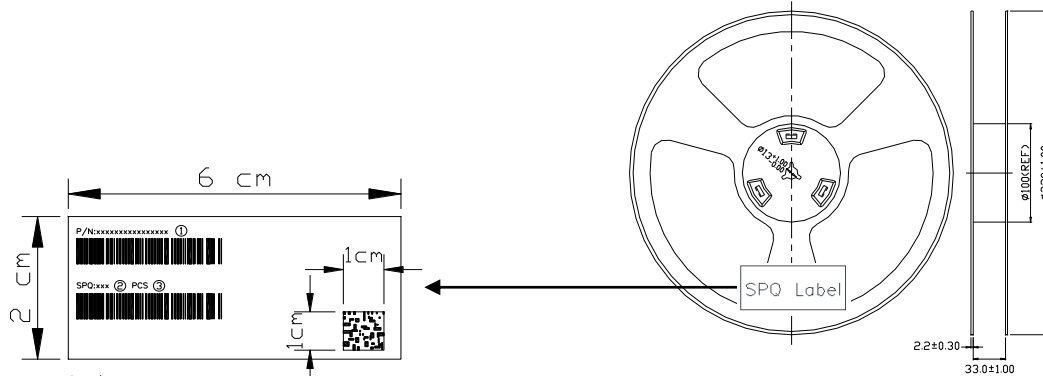
### Schedule

2016, September, Taoglas will input this new packaging into productions.

### Forecast Estimated Transition Date

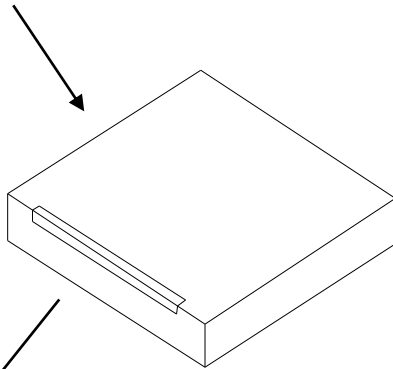
Sep/2016

### Illustration of Change Old Package

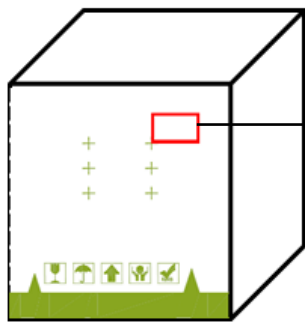


①P/N: Taoglas的品號  
 ②SPQ QTY: SPQ的數量  
 ③Unit:每一數量的單位

Vacuum packaging



Carton-Inside

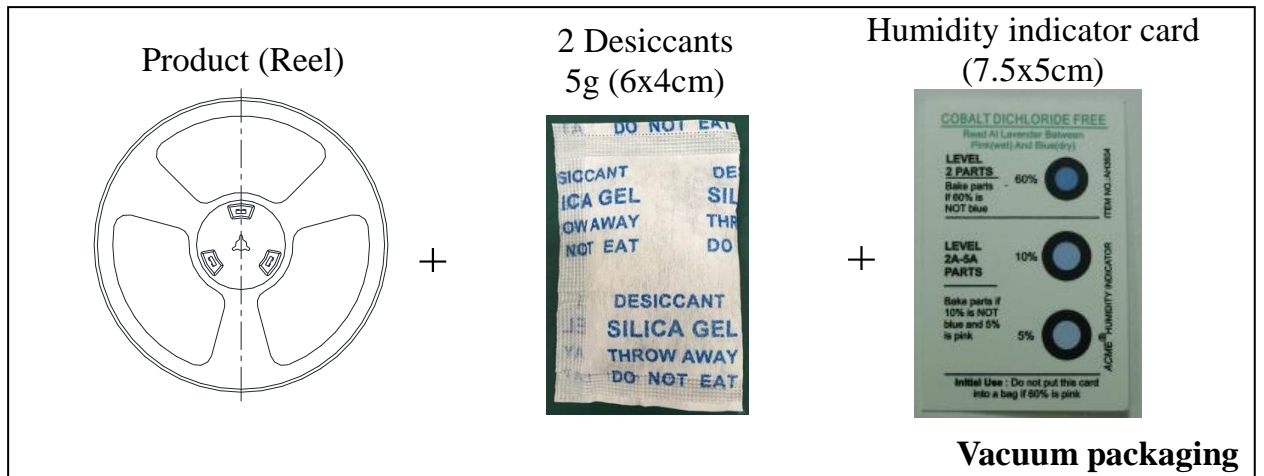


Carton

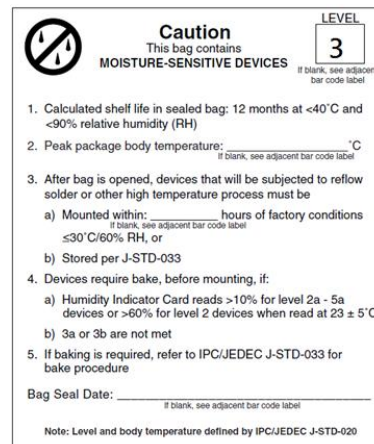


Shipping Label

### New Package



### Caution Label



**Caution**  
This bag contains **MOISTURE-SENSITIVE DEVICES**

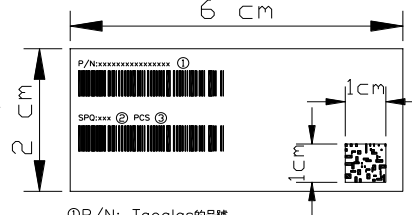
LEVEL **3**  
If blank, see adjacent bar code label

- Calculated shelf life in sealed bag: 12 months at <math><40^{\circ}\text{C}</math> and <math><90\%</math> relative humidity (RH)
- Peak package body temperature: \_\_\_\_\_  $^{\circ}\text{C}$   
If blank, see adjacent bar code label
- After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
  - Mounted within: \_\_\_\_\_ hours of factory conditions  
If blank, see adjacent bar code label  
 $\leq 30^{\circ}\text{C}/60\% \text{ RH}$ , or
  - Stored per J-STD-033
- Devices require bake, before mounting, if:
  - Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at  $23 \pm 5^{\circ}\text{C}$
  - 3a or 3b are not met
- If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: \_\_\_\_\_  
If blank, see adjacent bar code label

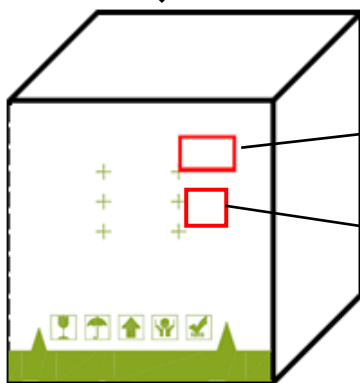
Note: Level and body temperature defined by IPC/JEDEC J-STD-020

### SPQ Label



①P/N: Taoglas的品號  
②SPQ QTY: SPQ的數量  
③Unit:每一數量的單位

### Carton-Inside



### Carton

### Shipping Label

### MSID Label

